

Filename: PMP5185A_BOM.xls

Date: May 30, 2013

PMP5185A BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
0	C1	Open	Capacitor, multi pattern, SM 1210 to E case + F THole	Multi sizes	Engineering Only	{MFR}
1	C10	0.01uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	GRM39yyyxxxKvvvA	muRata
1	C3	10uF	10uF Capacitor, Ceramic, 25V, X5R, 20%	1210	Std	Std
1	C5	47uF	Capacitor, Ceramic, 6.3V, X5R, 20%	1210	Std	Std
1	C6	0.1uF	0.1uF Capacitor, Ceramic, 25V, X7R, 15%	0603	Std	muRata
1	C7	3900pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	GRM39yyyxxxKvvvA	muRata
1	C8	27pF	Capacitor, Ceramic, 50V, NPO, 10%	0603	GRM39yyyxxxKvvvA	muRata
1	D1	B260	Diode, Schottky, 2A, 40V	SMB	B260	Motorola
1	ENA2	EN	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
2	GND.2, GND2	GND	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
2	J1, J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
1	L1	220uH	Inductor, SMT, 0.88A, 756milliohm	0.402 x 0.394 inch	MSS1038-224KL	Coilcraft
1	PH2	PH	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
3	PWRGD2	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
0	R1	NP	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R3	51Ohm	Resistor, Chip, 1/16W, 5%: for Bode loop testing only	0603	CRCW0603-xxxx-J	Vishay
1	R4	46.4k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R6	1.4Meg	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R7	1 Meg	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
0	R8	NP	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R9	191k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	SS/TR2	SS	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
2	TP1, TP2	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
1	U1**	TPS54040DGQ	IC,DC-DC Converter, 42Vin max, 0.5A output	MSOP-10	TPS54040DGQ	TI
1	VIN2	VIN	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
1	VOUT2	VOUT	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
1	PCB		HPA429 rev E1 3" by 3"			

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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